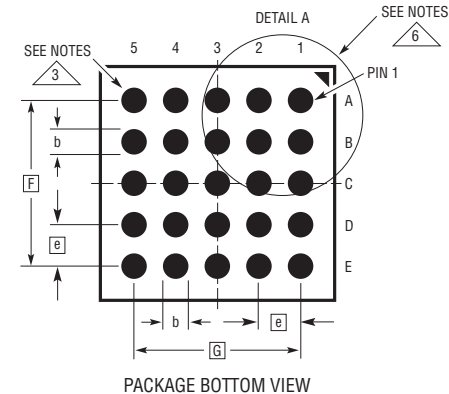
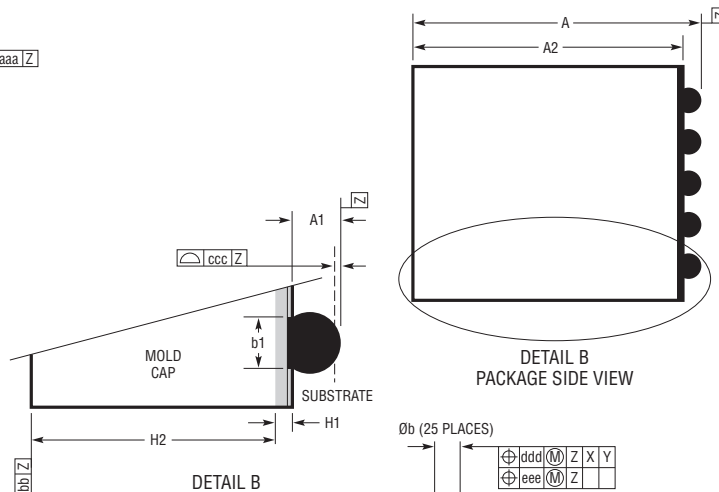
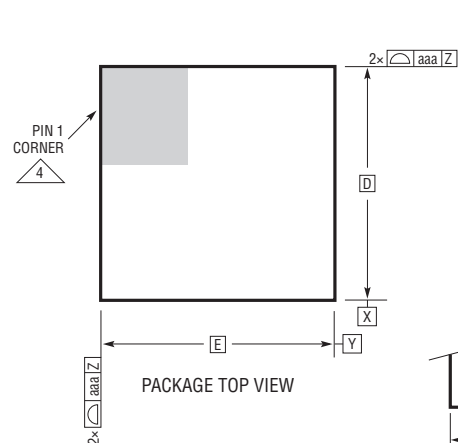
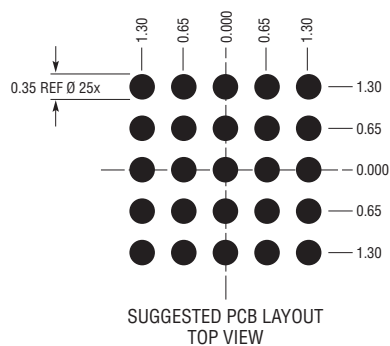


BGA Package
25-Lead (4mm × 4mm × 4.62mm)
(Reference LTC DWG# 05-08-7028 Rev 0)



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. BALL DESIGNATION PER JEP95
 4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE

6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.46	4.62	4.78	
A1	0.23	0.30	0.37	BALL HT
A2	4.23	4.32	4.41	
b	0.35	0.40	0.45	BALL DIMENSION
b1	0.32	0.35	0.38	PAD DIMENSION
D		4.00		
E		4.00		
e		0.65		
F		2.60		
G		2.60		
H1		0.32		SUBSTRATE THK
H2		4.00		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.10	
ddd			0.15	
eee			0.08	

